



Material Content Data Sheet



Sales Product Name		IPU60R1K0CE		Issued		1. August 2018		
MA#		MA001279188						
Package		PG-TO251-3-341		Weight*		381.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.144	0.56	0.56	5619	5619
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		180	
	non noble metal	iron	7439-89-6	0.229	0.06		601	
	non noble metal	copper	7440-50-8	228.946	60.02	60.10	600082	600863
	non noble metal	aluminium	7429-90-5	0.429	0.11	0.11	1125	1125
wire	inorganic material	antimonytrioxide	1309-64-4	1.736	0.46		4551	
encapsulation	plastics	brominated resin	-	1.860	0.49		4876	
	organic material	carbon black	1333-86-4	1.984	0.52		5201	
	plastics	epoxy resin	-	16.741	4.39		43880	
	inorganic material	silicondioxide	60676-86-0	101.689	26.65	32.51	266532	325040
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9803	9803
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1334	1334
solder	non noble metal	tin	7440-31-5	0.045	0.01		118	
	noble metal	silver	7440-22-4	0.056	0.01		147	
	non noble metal	lead	7439-92-1	2.144	0.56	0.58	5621	5886
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.00		50	
	non noble metal	copper	7440-50-8	19.177	5.03	5.03	50265	50330
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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